Journal of ELECTRONIC MATERIALS, Vol. 46, No. 11, 2017
DOI: 10.1007/s11664-017-5716-1
© 2017 The Minerals, Metals & Materials Society

CrossMark

# Erratum to: Effects of Forming Processes on the Microstructure and Solderability of Sn-3.5Ag Eutectic Solder Ribbons as well as the Mechanical Properties of Solder Joints

SHENGFA LIU,[1] ZHEBING HU,[1,3] JIERAN XIONG,[2] GUANGHUA TAN,[1] WENYONG XIONG,[1] CHEN CHEN,[1] and SHANGYU HUANG[1]

1.—School of Materials Science and Engineering, Wuhan University of Technology, Wuhan 430070, China. 2.—Shanwei Bolin Electronic Package Material Co., Ltd., Shanwei 516600, China. 3.—e-mail: huzhebing_123@163.com

**Erratum to: Journal of ELECTRONIC MATERIALS DOI: 10.1007/s11664-017-5672-9**

In the third paragraph of “Introduction” in the original article, the term $Ag_3Snm$ should be $Ag_3Sn$.

The original article has been updated.

(Published online August 16, 2017)
The online version of the original article can be found under doi:10.1007/s11664-017-5672-9.